

# E1UGA18-3.579545M TR

<b>Lead Free</b>  <b>COMPLIANT</b>	<b>RoHS</b>  <b>COMPLIANT</b>	<b>ChinaRoHS</b>  <b>COMPLIANT</b>	<b>REACH</b> <b>SVHC 161</b> Dec 17, 2014 <b>COMPLIANT</b>
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## ITEM DESCRIPTION

Quartz Crystal Resonator HC49/US Short Thru-Hole 2.5mm Height Metal Resistance Weld Seal 3.579545MHz  $\pm 15$ ppm at 25°C,  $\pm 30$ ppm over 0°C to +70°C 18pF Parallel Resonant

## ELECTRICAL SPECIFICATIONS

<b>Nominal Frequency</b>	3.579545MHz
<b>Frequency Tolerance/Stability</b>	$\pm 15$ ppm at 25°C, $\pm 30$ ppm over 0°C to +70°C
<b>Aging at 25°C</b>	$\pm 5$ ppm/year Maximum
<b>Load Capacitance</b>	18pF Parallel Resonant
<b>Shunt Capacitance</b>	7pF Maximum
<b>Equivalent Series Resistance</b>	200 Ohms Maximum
<b>Mode of Operation</b>	AT-Cut Fundamental
<b>Drive Level</b>	1mWatt Maximum
<b>Storage Temperature Range</b>	-40°C to +125°C
<b>Insulation Resistance</b>	500 Megaohms Minimum (Measured at 100Vdc)

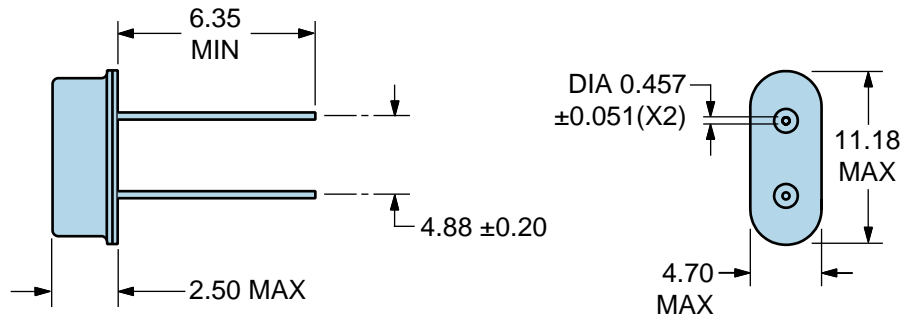
## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Lead Integrity</b>	MIL-STD-883, Method 2004
<b>Mechanical Shock</b>	MIL-STD-202, Method 213, Condition C
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)

LINE	MARKING
1	<b>E3.5795M</b> <i>E=Ecliptek Designator</i>



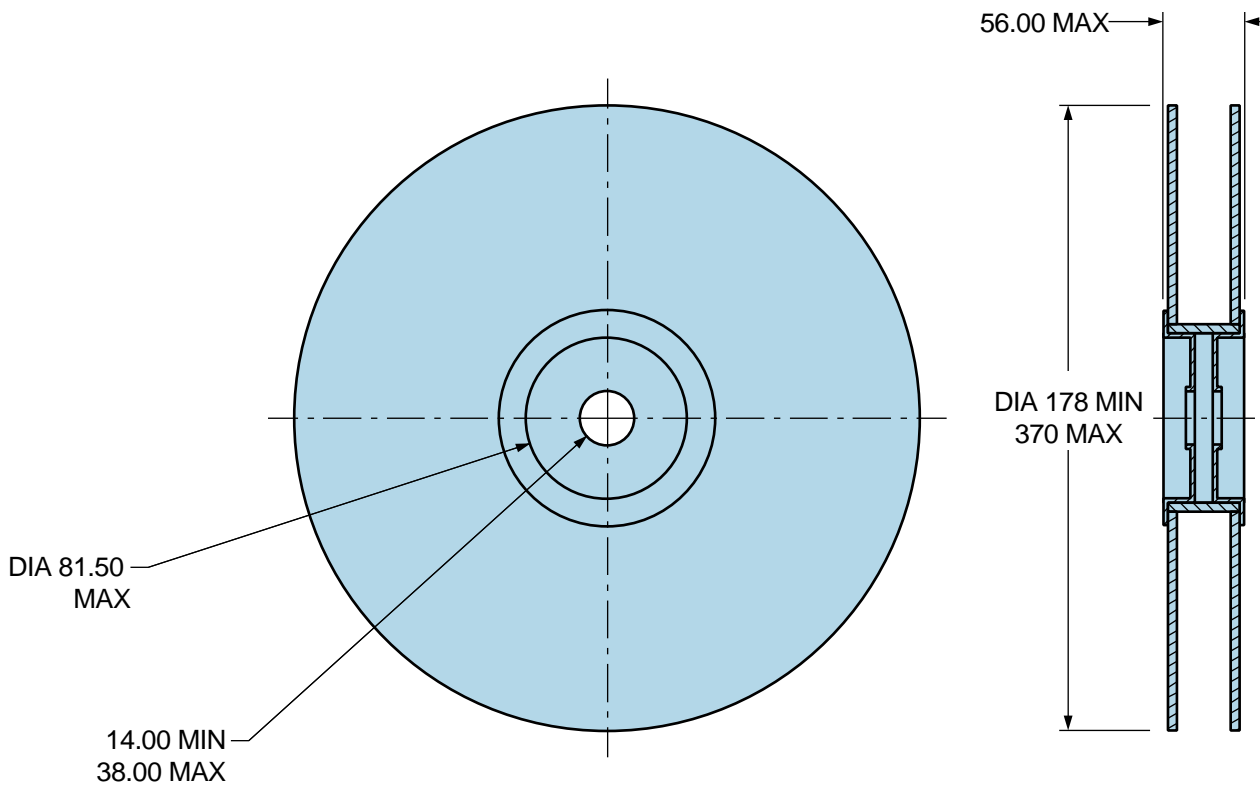
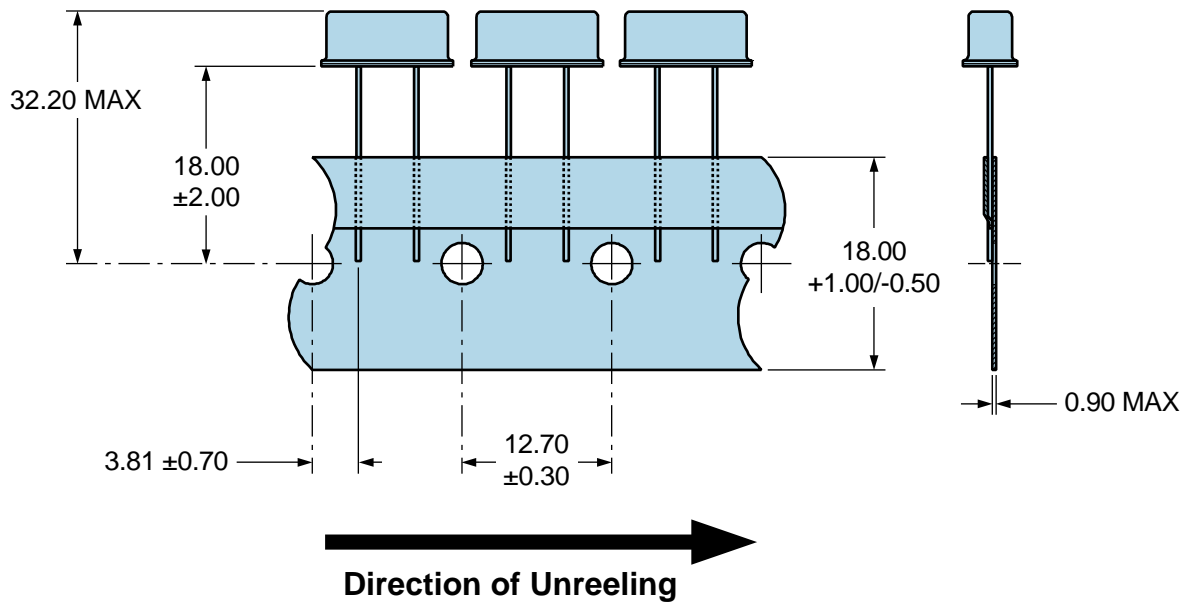
# E1UGA18-3.579545M TR

## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

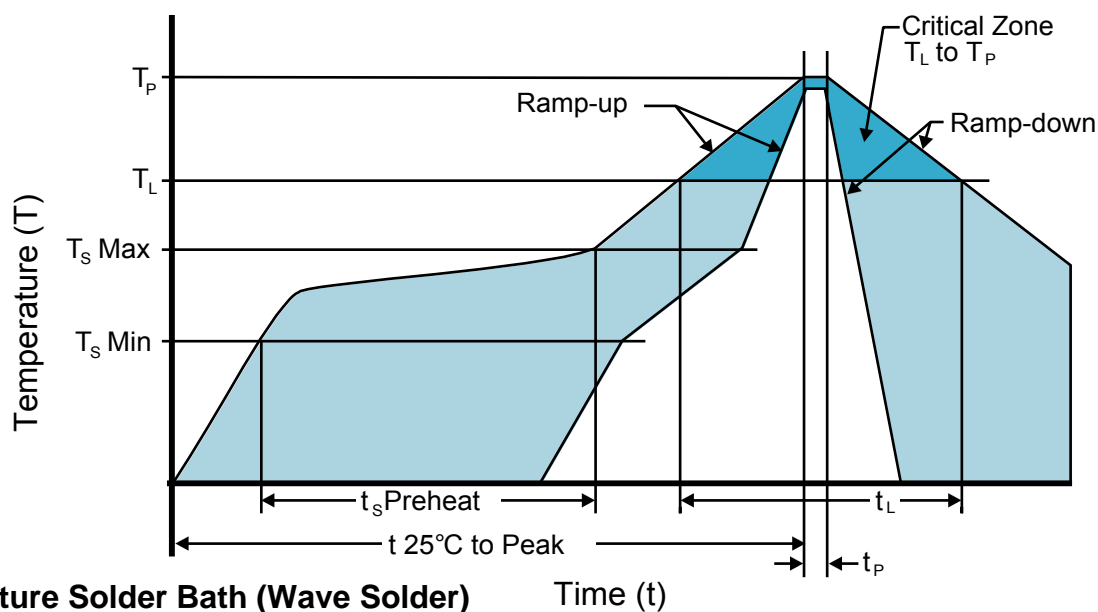
All Dimensions in Millimeters

Compliant to EIA-468



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## Recommended Solder Reflow Methods

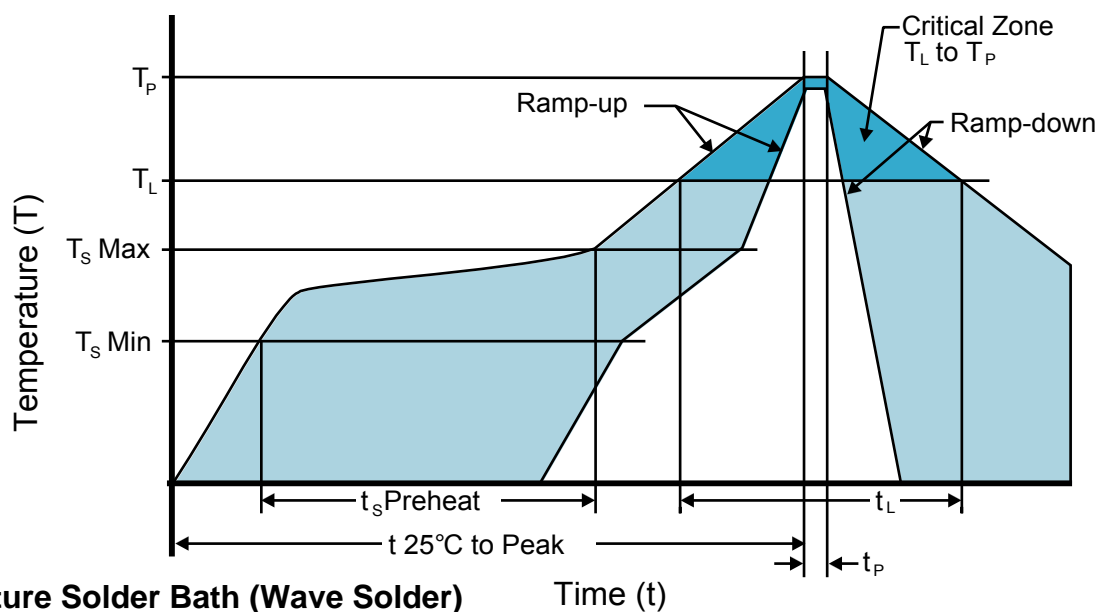


### High Temperature Solder Bath (Wave Solder) Time (t)

<b>Ts MAX to T<sub>L</sub> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (T <sub>s</sub> MIN)	150°C
- Temperature Typical (T <sub>s</sub> TYP)	175°C
- Temperature Maximum (T <sub>s</sub> MAX)	200°C
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds
<b>Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (T <sub>L</sub> )	217°C
- Time (t <sub>L</sub> )	60 - 150 Seconds
<b>Peak Temperature (T<sub>P</sub>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (T<sub>P</sub> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (t<sub>p</sub>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to back of PCB board and device leads only.

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## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder) Time (t)

**Ts MAX to Tl (Ramp-up Rate)** 5°C/Second Maximum

#### Preheat

- Temperature Minimum (Ts MIN) N/A  
 - Temperature Typical (Ts TYP) 150°C  
 - Temperature Maximum (Ts MAX) N/A  
 - Time (ts MIN) 30 - 60 Seconds

**Ramp-up Rate (Tl to Tp)** 5°C/Second Maximum

#### Time Maintained Above:

- Temperature (Tl) 150°C  
 - Time (tL) 200 Seconds Maximum

**Peak Temperature (Tp)** 245°C Maximum

**Target Peak Temperature (Tp Target)** 245°C Maximum 1 Time / 235°C Maximum 2 Times

**Time within 5°C of actual peak (tp)** 5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times

**Ramp-down Rate** 5°C/Second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

**Additional Notes** Temperatures shown are applied to back of PCB board and device leads only.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to back of PCB board and device leads only.)